

C

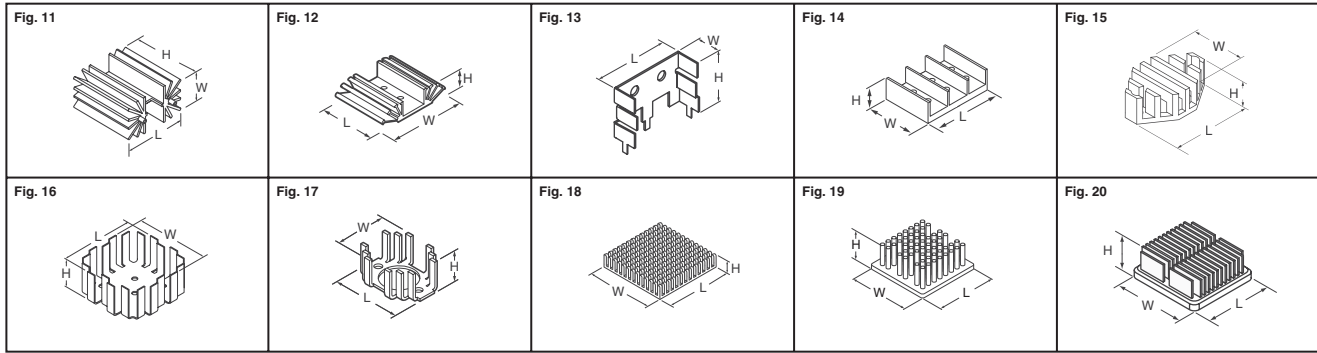


Fig.	Description	Dimensions - Inch (mm) L x W x H	Thermal Res. C/Watt	Digi-Key Part No.	Price Each	CTS Part No.
					1 10 100	
18	Various Semiconductor, Adhesive Backed	1.31 x 1.31 x .355 (33.27 x 33.27 x 9.02)	16.10	294-1100-ND	3.30 2.97 2.31	BDN13-3CB/A01
	Various Semiconductor, Adhesive Backed	1.41 x 1.41 x .355 (35.81 x 35.81 x 9.02)	16.20	294-1101-ND	5.11 4.60 3.58	BDN14-3CB/A01
	Various Semiconductor, Adhesive Backed	1.51 x 1.51 x .355 (38.35 x 38.35 x 9.02)	15.10	294-1102-ND	3.98 3.58 2.79	BDN15-3CB/A01
	Various Semiconductor, Adhesive Backed	1.61 x 1.61 x .355 (40.89 x 40.89 x 9.02)	13.50	294-1103-ND	4.08 3.67 2.86	BDN16-3CB/A01
	Various Semiconductor, Adhesive Backed	1.71 x 1.71 x .355 (43.43 x 43.43 x 9.02)	11.50	294-1111-ND	4.18 3.77 2.93	BDN17-3CB/A01
	Various Semiconductor, Adhesive Backed	1.81 x 1.81 x .355 (45.97 x 45.97 x 9.02)	10.80	294-1104-ND	4.43 3.99 3.10	BDN18-3CB/A01
19	Various SMT Semiconductor	1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6)	5.3	294-1125-ND	4.60 4.14 3.22	APR27-27-12CB
	Various SMT Semiconductor, with Thermal Tape	1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6)	5.3	294-1126-ND	5.97 5.38 4.19	APR27-27-12CB/A01
	Various SMT Semiconductor, with Short Clip	1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6)	5.3	294-1127-ND	6.25 5.63 4.38	APR27-27-12CB/S
	Various SMT Semiconductor, with Medium Clip	1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6)	5.3	294-1128-ND	6.25 5.63 4.38	APR27-27-12CB/M
	Various SMT Semiconductor, with Tall Clip	1.026 x 1.026 x .457 (26.6 x 26.6 x 11.6)	5.3	294-1129-ND	6.25 5.63 4.38	APR27-27-12CB/T
	Various SMT Semiconductor	1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6)	3.8	294-1130-ND	5.15 4.64 3.61	APR33-33-12CB
	Various SMT Semiconductor, with Thermal Tape	1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6)	3.8	294-1131-ND	6.77 6.10 4.74	APR33-33-12CB/A01
	Various SMT Semiconductor, with Short Clip	1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6)	3.8	294-1132-ND	6.83 6.15 4.78	APR33-33-12CB/S
	Various SMT Semiconductor, with Medium Clip	1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6)	3.8	294-1133-ND	6.83 6.15 4.78	APR33-33-12CB/M
	Various SMT Semiconductor, with Tall Clip	1.284 x 1.284 x .457 (32.6 x 32.6 x 11.6)	3.8	294-1134-ND	6.83 6.15 4.78	APR33-33-12CB/T
	Various SMT Semiconductor	1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6)	3.3	294-1135-ND	5.30 4.77 3.71	APR38-38-12CB
	Various SMT Semiconductor, with Thermal Tape	1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6)	3.3	294-1136-ND	6.35 5.72 4.45	APR38-38-12CB/A01
	Various SMT Semiconductor, with Short Clip	1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6)	3.3	294-1137-ND	6.95 6.26 4.87	APR38-38-12CB/S
	Various SMT Semiconductor, with Medium Clip	1.461 x 1.461 x .457 (37.1 x 37.1 x 11.6)	3.3	294-1138-ND	6.95 6.26 4.87	APR38-38-12CB/M
20	Heatsink Low-Profile Forged	.748 x .748 x .248 (19 x 19 x 6.3)	7.05	294-1145-ND	4.75 4.28 3.33	APF19-19-06CB
	Heatsink Forged with Adhesive Tape	.748 x .748 x .248 (19 x 19 x 6.3)	7.05	294-1146-ND	5.81 5.24 4.07	APF19-19-06CB/A01
	Heatsink Low-Profile Forged	.748 x .748 x .374 (19 x 19 x 9.5)	5.25	294-1147-ND	4.79 4.32 3.36	APF19-19-10CB
	Heatsink Forged with Adhesive Tape	.748 x .748 x .374 (19 x 19 x 9.5)	5.25	294-1148-ND	5.94 5.35 4.16	APF19-19-10CB/A01
	Heatsink Low-Profile Forged	.748 x .748 x .500 (19 x 19 x 12.7)	3.95	294-1149-ND	5.94 5.35 4.16	APF19-19-13CB
	Heatsink Forged with Adhesive Tape	.748 x .748 x .500 (19 x 19 x 12.7)	3.95	294-1150-ND	5.94 5.35 4.16	APF19-19-13CB/A01
	Heatsink Low-Profile Forged	1.181 x 1.181 x .248 (30 x 30 x 6.3)	4.35	294-1151-ND	5.93 5.34 4.15	APF30-30-06CB
	Heatsink Forged with Adhesive Tape	1.181 x 1.181 x .248 (30 x 30 x 6.3)	4.35	294-1152-ND	7.51 6.77 5.26	APF30-30-06CB/A01
	Heatsink Low-Profile Forged	1.181 x 1.181 x .374 (30 x 30 x 9.5)	3.25	294-1153-ND	6.13 5.52 4.30	APF30-30-10CB
	Heatsink Forged with Adhesive Tape	1.181 x 1.181 x .374 (30 x 30 x 9.5)	3.25	294-1154-ND	7.74 6.97 5.42	APF30-30-10CB/A01
	Heatsink Low-Profile Forged	1.181 x 1.181 x .500 (30 x 30 x 12.7)	2.45	294-1155-ND	6.58 5.92 4.61	APF30-30-13CB
	Heatsink Forged with Adhesive Tape	1.181 x 1.181 x .500 (30 x 30 x 12.7)	2.45	294-1156-ND	7.29 6.57 5.11	APF30-30-13CB/A01
	Heatsink Low-Profile Forged	1.575 x 1.575 x .248 (40 x 40 x 6.3)	3.30	294-1157-ND	7.91 7.12 5.54	APF40-40-06CB
	Heatsink Forged with Adhesive Tape	1.575 x 1.575 x .248 (40 x 40 x 6.3)	3.30	294-1158-ND	8.10 7.29 5.67	APF40-40-06CB/A01
	Heatsink Low-Profile Forged	1.575 x 1.575 x .374 (40 x 40 x 9.5)	2.50	294-1159-ND	7.29 6.57 5.11	APF40-40-10CB
	Heatsink Forged with Adhesive Tape	1.575 x 1.575 x .374 (40 x 40 x 9.5)	2.50	294-1160-ND	8.33 7.50 5.84	APF40-40-10CB/A01
	Heatsink Low-Profile Forged	1.575 x 1.575 x .500 (40 x 40 x 12.7)	1.90	294-1161-ND	7.53 6.78 5.27	APF40-40-13CB
	Heatsink Forged with Adhesive Tape	1.575 x 1.575 x .500 (40 x 40 x 12.7)	1.90	294-1162-ND	9.11 8.20 6.38	APF40-40-13CB/A01

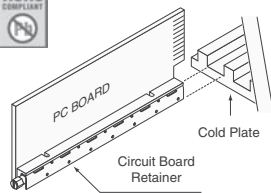
◆ RoHS Compliant

ZIF III Circuit Board Retainers

The ZIF retainer is a self-contained, precision assembly that provides highly effective thermal interface between the circuit board and cold plate. CTS ZIF III features a quick, quarter-turn locking mechanism that provides for a positive and fast assembly. The unique locking design produces a uniform pressure distribution along the PCB edge for optimal heat transfer and resistance to extreme shock and vibration.

Features:

- PC board mountable (screw mounting)
- Positive 1/4 turn locking
- Field maintainable
- Superior mechanical retention
- Thermally efficient, 1.2°C-inch/Watt



Description	Digi-Key Part No.	Price Each	CTS Part No.
		1 10 100	
PCB Retainer – Hex Head Drive, 4.50" Housing Assembly, Left Hand Part	294-1163-ND	66.24 55.20 48.76	Z3A45SBSBNL
PCB Retainer – Hex Head Drive, 4.50" Housing Assembly, Right Hand Part	294-1164-ND	66.24 55.20 48.76	Z3A45SBSBNR
PCB Retainer – Hex Head Drive, 5.25" Housing Assembly, Left Hand Part	294-1165-ND	69.35 57.80 51.06	Z3A52SBSBNL
PCB Retainer – Hex Head Drive, 5.25" Housing Assembly, Right Hand Part	294-1166-ND	69.35 57.80 51.06	Z3A52SBSBNR

More Product Available Online: www.digkey.com